

ABSTRACT OF THE DISCLOSURE

- [44] A radio frequency module packaging system and method characterized by compact package size, reduced packaging loss and variation, and reduced heat generation. The radio frequency module is provided with via holes, electrodes for signals, and grounding electrodes on the surface of a substrate. Under the electrodes for signals, via holes are made, and on both sides of the electrodes for signals, grounding via holes are made so that these via holes form microstrip lines. Both input and output ends of a high frequency circuit including an active device, formed as the module's functional circuit on the substrate, are routed through the via holes and connected to another circuit.